

L1384QMP/ID

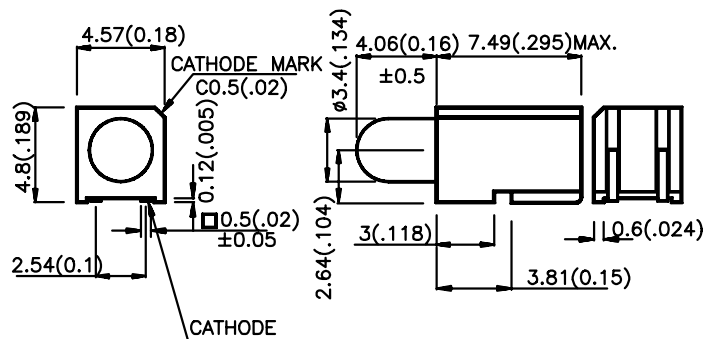
### Features

- PRE-TRIMMED LEADS FOR PC MOUNTING.
- CAN BE ASSEMBLED WITH EACH OTHER.
- I.C. COMPATIBLE.
- BLACK CASE ENHANCES CONTRAST RATIO.
- WIDE VIEWING ANGLE.
- HIGH RELIABILITY LIFE MEASURED IN YEARS.
- HOUSING MATERIAL: PPA
- PACKAGE : 1000PCS / REEL.

### Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

### Package Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25$  (0.01") unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

## Selection Guide

Part No.	Dice	Case-Color	Iv (mcd) @ 10 mA		Viewing Angle
			Min.	Typ.	2θ1/2
L1384QMP/ID	HIGH EFFICIENCY RED (GaAsP/GaP)	RED DIFFUSED	12	20	60°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

## Electrical / Optical Characteristics at T<sub>A</sub>=25°C

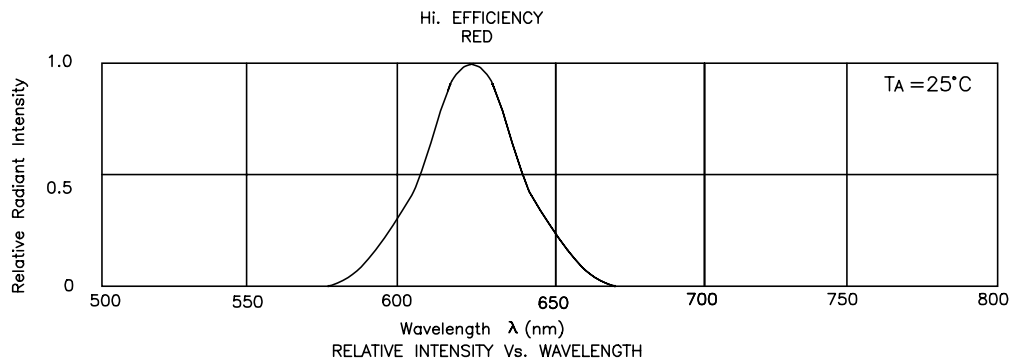
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ <sub>peak</sub>	Peak Wavelength	High Efficiency Red	627		nm	IF=20mA
λ <sub>D</sub>	Dominate Wavelength	High Efficiency Red	625		nm	IF=20mA
Δλ <sub>1/2</sub>	Spectral Line Halfwidth	High Efficiency Red	45		nm	IF=20mA
C	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
V <sub>F</sub>	Forward Voltage	High Efficiency Red	2.0	2.5	V	IF=20mA
I <sub>r</sub>	Reverse Current	All		10	μA	VR = 5V

## Absolute Maximum Ratings at T<sub>A</sub>=25°C

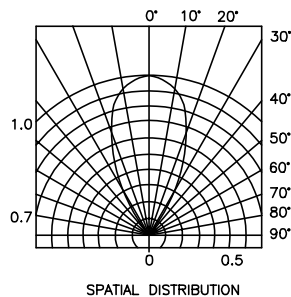
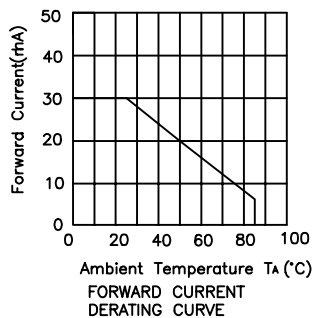
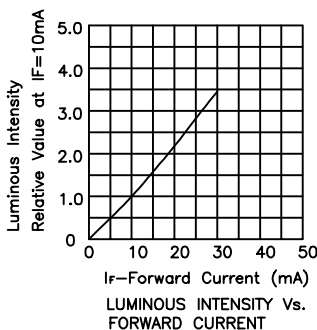
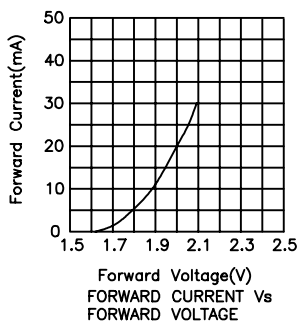
Parameter	High Efficiency Red	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	160	mA
Reverse Voltage	5	V
Operation/Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

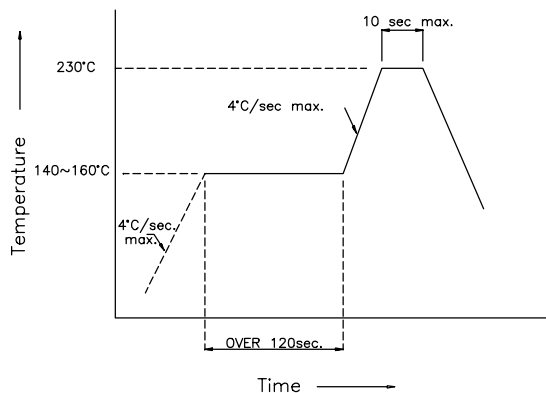


## High Efficiency Red L1384QMP/ID

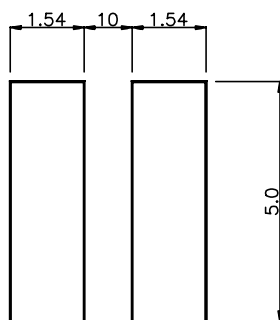


## L1384QMP/ID SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process."



## Recommended Soldering Pattern



## Tape Specifications

